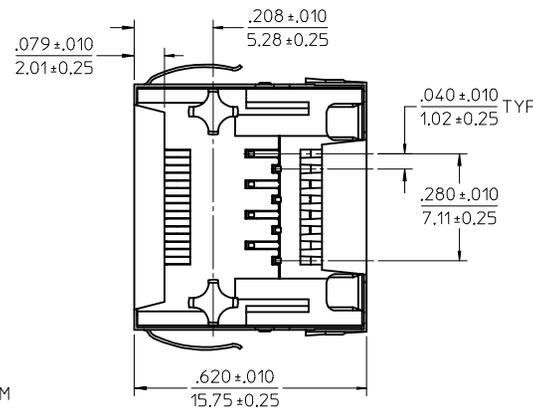
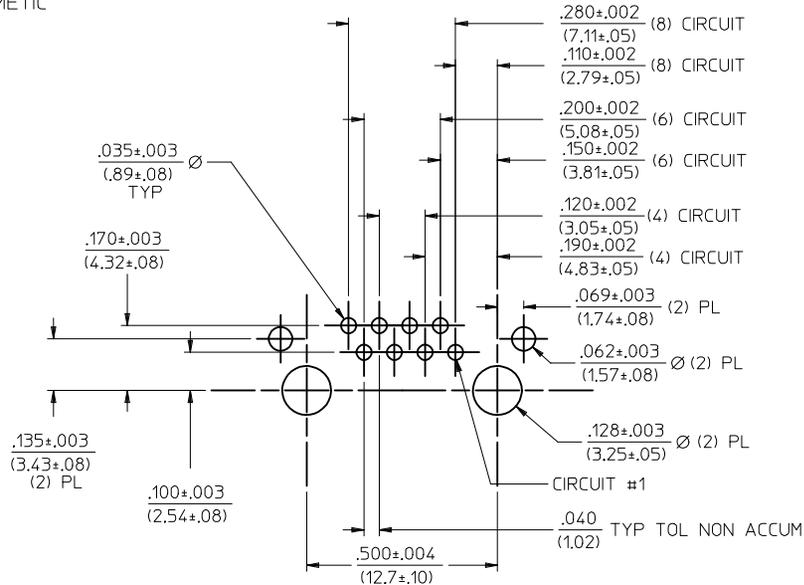
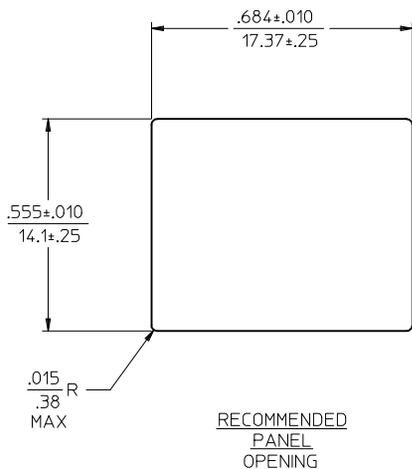
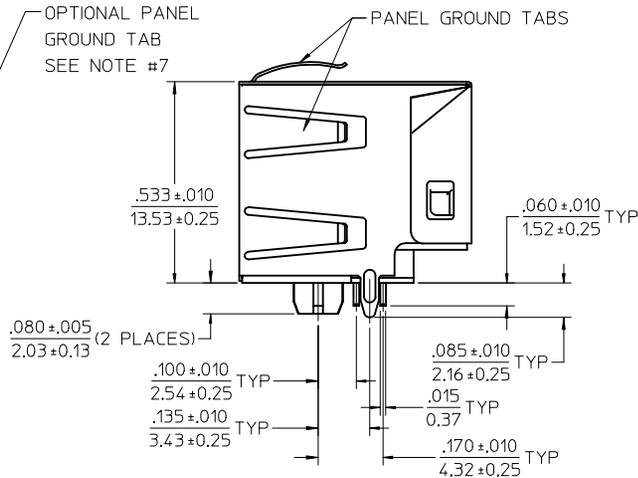
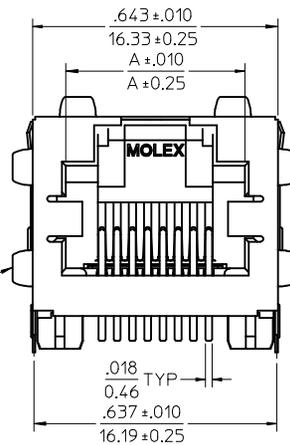


NOTES

- 1) MATERIAL:
HOUSING: GLASS FILLED NYLON, 94V-0 COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE, .015/(0.38) THICK
SHIELD: BRASS
- 2) PLATING:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
SHIELD:
100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES
(1.27 MICROMETERS) COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN
- 3) PRODUCT SPECIFICATION:
CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003
- 4) PACKAGING OPTIONS:
CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS
PER PACKAGING SPECIFICATION PK-44380-005
OPTION (44380-2004) PACKAGED IN TAPE AND REEL
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY
- 6) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS
- 7) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
- 8) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



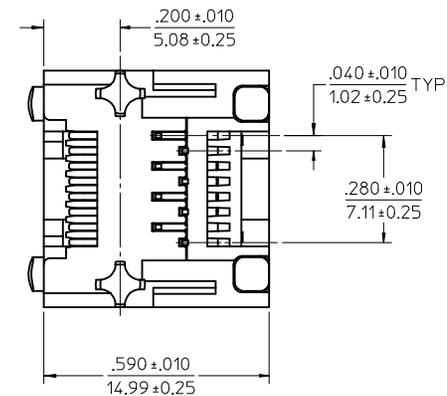
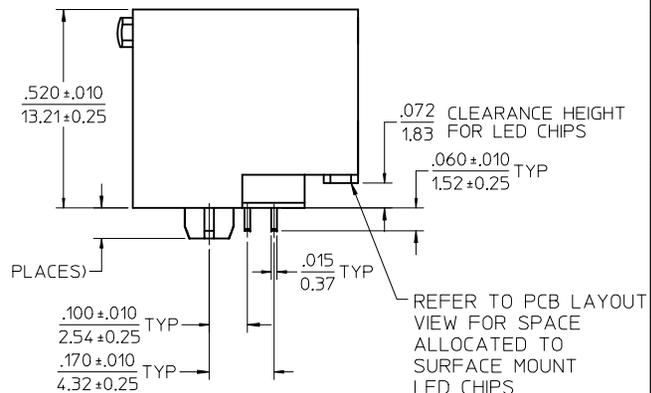
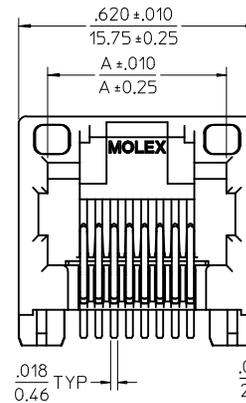
PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PC BOARD THICKNESS: .039/1.00

MATERIAL NUMBER	CONNECTOR SIZE	DIM. "A"	CIRCUITS	PANEL GROUND TABS
44380-0004	8	.470/11.94	8	ALL
44380-0005	6	.389/9.88	6	ALL
44380-0006	6	.389/9.88	4	ALL
44380-0013	8	.470/11.94	8	SEE NOTE #7
44380-0014	6	.389/9.88	6	SEE NOTE #7
44380-0015	6	.389/9.88	4	SEE NOTE #7
44380-2004	8	.470/11.94	8	ALL

SEE SHEET 1 EC NO: UCP2015-0148 DRAWING NO: 2014/07/16 CHKD: JEBLL APPR: FSM/TH 2015/05/19	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> <tr> <td>4 PLACES ±</td> <td>---</td> <td>±---</td> </tr> <tr> <td>3 PLACES ±</td> <td>---</td> <td>±---</td> </tr> <tr> <td>2 PLACES ±</td> <td>---</td> <td>±---</td> </tr> <tr> <td>1 PLACE ±</td> <td>---</td> <td>±---</td> </tr> <tr> <td>0 PLACE ±</td> <td>---</td> <td>±---</td> </tr> </table>		mm	INCH	4 PLACES ±	---	±---	3 PLACES ±	---	±---	2 PLACES ±	---	±---	1 PLACE ±	---	±---	0 PLACE ±	---	±---	DIMENSION STYLE IN/MM	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
				mm	INCH																			
4 PLACES ±	---	±---																						
3 PLACES ±	---	±---																						
2 PLACES ±	---	±---																						
1 PLACE ±	---	±---																						
0 PLACE ±	---	±---																						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE CHART	DATE 1999/04/09	DATE 1999/04/09	DATE 1999/04/09	TITLE INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)	SHEET NO. 2 OF 5																		

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

- NOTES
- MATERIAL:
HOUSING:
GLASS FILLED NYLON, 94V-0, COLOR: BLACK
TERMINALS:
PHOSPHOR BRONZE, .015/(0.38) THK
LIGHTPIPE:
POLYCARBONATE- WAVE OR HAND SOLDER ONLY
(NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW
SOLDER PROCESSES)
POLYSULFONE - MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
 - PLATING:
TERMINAL:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
 - PACKAGING SPECIFICATION:
CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003
 - PACKAGING:
PER PACKAGING SPECIFICATION PK-43860-004
 - APPLICATION SPECIFICATION: AS-43860-001.
 - ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS.
 - REFER TO PAGE (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



MATERIAL NUMBER	LIGHTPIPE MATERIAL	CONNECTOR SIZE	DIM. "A"	CIRCUITS
44380-0007	POLYCARBONATE	8	.470/11.94	8
44380-0008	POLYCARBONATE	6	.389/9.88	6
44380-0009	POLYCARBONATE	6	.389/9.88	4
44380-0020	POLYSULFONE	8	.470/11.94	8
44380-0021	POLYSULFONE	6	.389/9.88	6
44380-0022	POLYSULFONE	6	.389/9.88	4

SEE SHEET 1	EC NO: UCP2015-0148	2014/07/16
	DRW: NGUYEN	2014/07/16
C2	CHKD: BELL	2014/07/16
	APPR: F. SMITH	2015/05/19

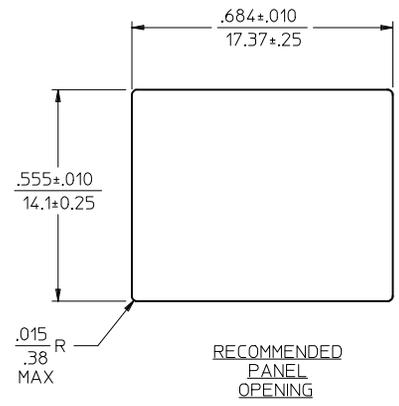
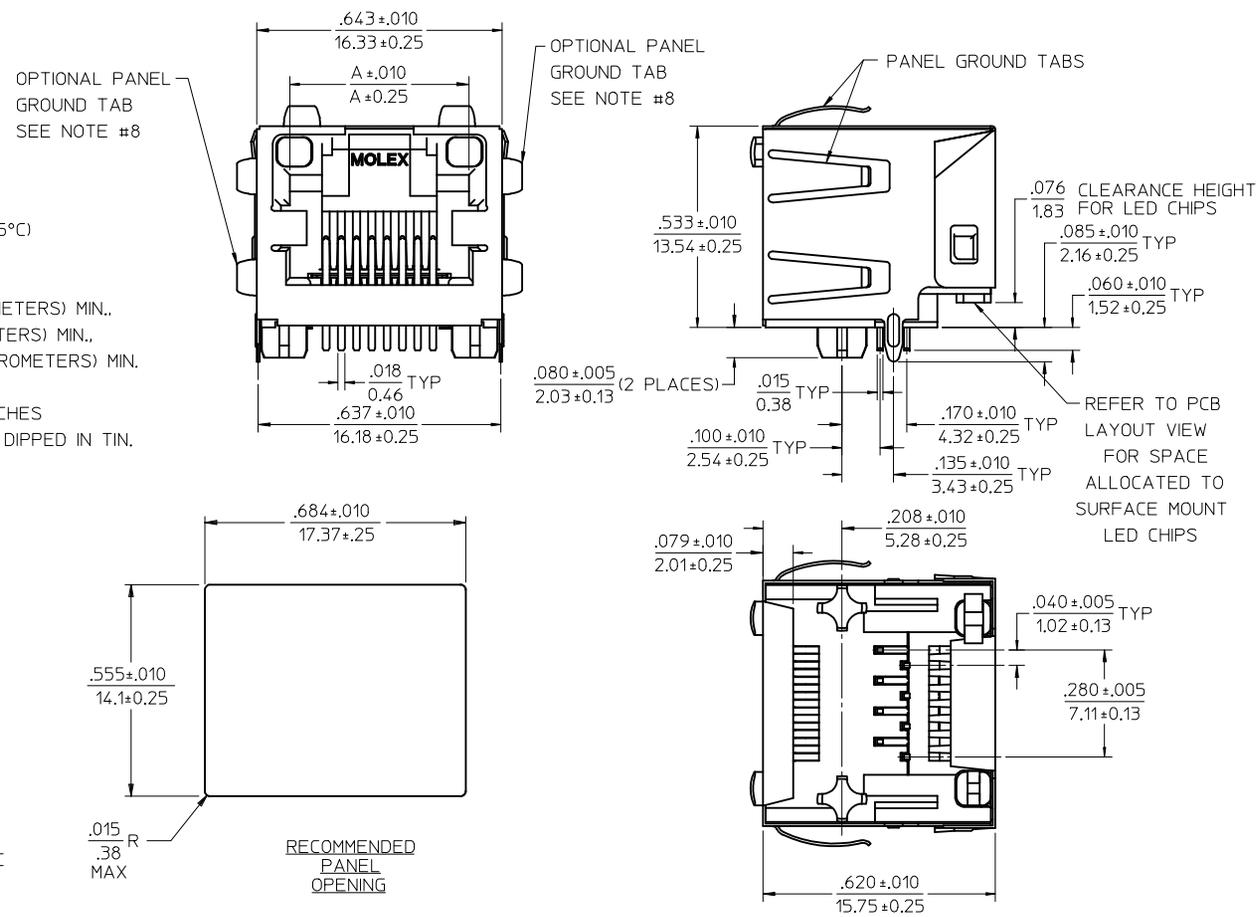
QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm	INCH
▽=0	4 PLACES ±	±
▽=0	3 PLACES ±	±
▽=0	2 PLACES ±	±
▽=0	1 PLACE ±	±
▽=0	0 PLACE ±	±
	ANGULAR ±1/2°	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
IN/MM		4:1	INCH	
DRAWN BY	DATE	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT) molex		
MAYO	1999/04/09			
CHECKED BY	DATE			
ROBERTS	1999/04/09			
APPROVED BY	DATE	SD-44380-001 DOCUMENT NO.		
ROBERTS	1999/04/09			
MATERIAL NO.	DATE	SHEET NO.		
SEE CHART		3 OF 5		

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
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NOTES

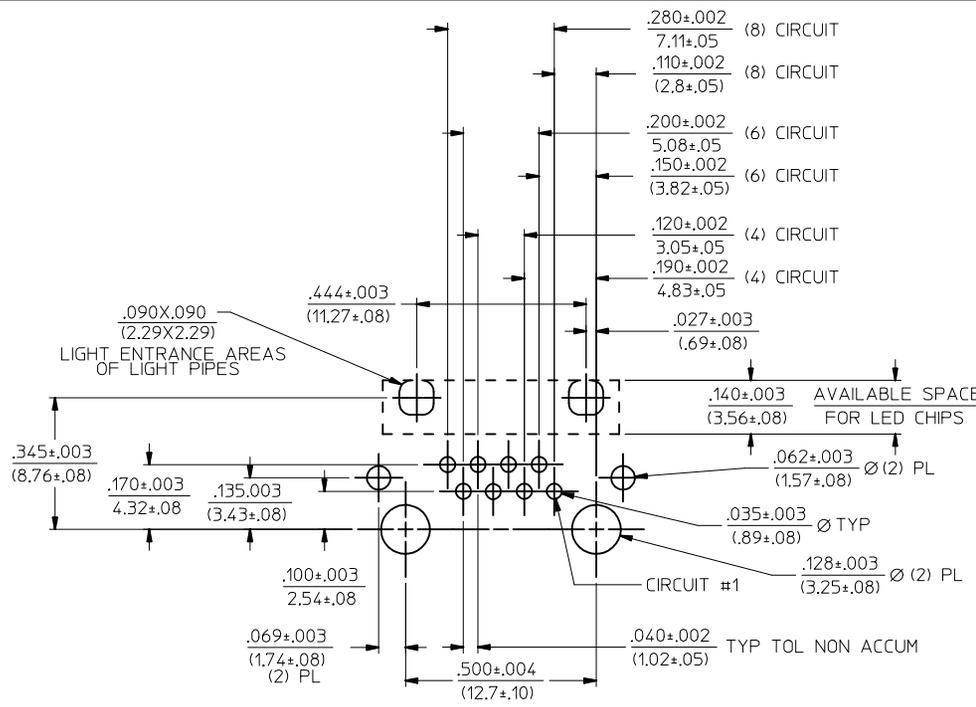
- 1) MATERIAL:
 - HOUSING: GLASS FILLED NYLON, 94V-0, COLOR: BLACK
 - TERMINALS: PHOSPHOR BRONZE, .015/(0.38) THK
 - SHIELD: BRASS
 - LIGHTPIPE: POLYCARBONATE - WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)
 - POLYSULFONE - MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
- 2) PLATING:
 - TERMINAL: SELECT GOLD IN CONTACT AREA: 50 MICRONS (1.27 MICROMETERS) MIN., SELECT TIN IN PC TAIL AREA: 100 MICRONS (2.54 MICROMETERS) MIN., WITH OVERALL NICKEL UNDERPLATE: 50 MICRONS (1.27 MICROMETERS) MIN.
 - SHIELD: 100 MICRONS (2.54 MICROMETERS) NICKEL OVER 50 MICRONS (1.27 MICROMETERS) COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN.
- 3) PRODUCT SPECIFICATION:
 - CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX PRODUCT SPECIFICATION PS-43860-003.
- 4) PACKAGING:
 - CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS PER PACKAGING SPECIFICATION PK-44380-005 .
- 5) APPLICATION SPECIFICATION: AS-43860-001.
- 6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 7) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS.
- 8) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
- 9) REFER TO SHEET (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
- 10) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



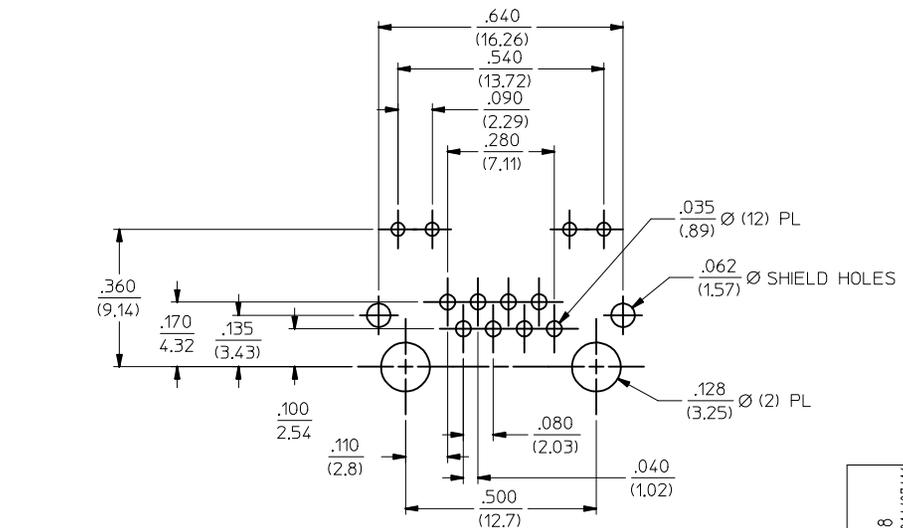
MATERIAL NUMBER	LIGHTPIPE MATERIAL	CONN SIZE	DIM. "A"	CIRCUITS	PANEL GROUND TABS
44380-0010	POLYCARBONATE	8	.470/11.94	8	ALL
44380-0011	POLYCARBONATE	6	.389/9.88	6	ALL
44380-0012	POLYCARBONATE	6	.389/9.88	4	ALL
44380-0016	POLYCARBONATE	8	.470/11.94	8	SEE NOTE #8
44380-0017	POLYCARBONATE	6	.389/9.88	6	SEE NOTE #8
44380-0018	POLYCARBONATE	6	.389/9.88	4	SEE NOTE #8
44380-1010	POLYSULFONE	8	.470/11.94	8	ALL
44380-1011	POLYSULFONE	6	.389/9.88	6	ALL
44380-1012	POLYSULFONE	6	.389/9.88	4	ALL
44380-1016	POLYSULFONE	8	.470/11.94	8	SEE NOTE #8
44380-1017	POLYSULFONE	6	.389/9.88	6	SEE NOTE #8
44380-1018	POLYSULFONE	6	.389/9.88	4	SEE NOTE #8

SEE SHEET 1
 EC NO: WGP2015-0148
 DRAWINGUYEN 2014/07/16
 CHKD:JBELL 2014/07/16
 APPR:FSMITH 2015/05/19

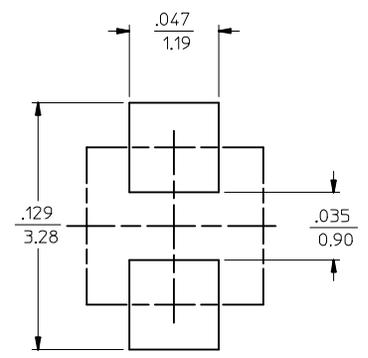
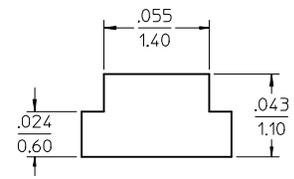
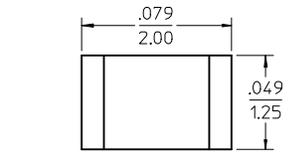
QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
▽=0	mm INCH	IN/MM	4:1	INCH	
▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT) molex DOCUMENT NO. SD-44380-001 SHEET NO. 4 OF 5		
▽=0	3 PLACES ± --- ± ---	MAYO 1999/04/09			
▽=0	2 PLACES ± --- ± ---	CHECKED BY DATE			
	1 PLACE ± --- ± ---	ROBERTS 1999/04/09			
	0 PLACE ± --- ± ---	APPROVED BY DATE			
	ANGULAR ±1/2°	ROBERTS 1999/04/09			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.			
		SEE CHART			
		SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



MOLEX RECOMMENDED
PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PC BOARD THICKNESS: .039/1.00



TYPICAL COMPETITION
PCB LAYOUT WITH
INTEGRAL LED'S
(SHOWN FOR REFERENCE ONLY)
RECOMMENDED PC BOARD THICKNESS: .039/1.00



RECOMMENDED SMT
LED DIMENSIONS
SCALE 20:1
(SEE NOTE 1)

RECOMMENDED SMT
LED SOLDER PATTERN
SCALE 20:1
(SEE NOTE 1)

NOTES:
1. FOR CROSS REFERENCE OF RECOMMENDED LEDS SEE MOLEX WEB SITE.

SEE SHEET 1 EC NO: UCP2015-0148 DRAWN: NGUYEN 2014/07/16 CHKD: BELL 2014/07/16 APPR: F. SMITH 2015/05/19	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
		4 PLACES ±	±	mm	INCH	DRAWN BY MAYO	DATE 1999/04/09	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)	
3 PLACES ±	±			CHECKED BY ROBERTS	DATE 1999/04/09	molex			
2 PLACES ±	±			APPROVED BY ROBERTS	DATE 1999/04/09				SD-44380-001
1 PLACE ±	±					SHEET NO. 5 OF 5			
0 PLACE ±	±								THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
ANGULAR ±1/2°				MATERIAL NO.		DOCUMENT NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SEE CHART					

Mouser Electronics

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